

### GENERAL DESCRIPTION

The ME9435 is the P-Channel logic enhancement mode power field effect transistors, using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone, notebook computer power management and other battery powered circuits, and in-line power loss that are needed in a very small outline surface mount package.

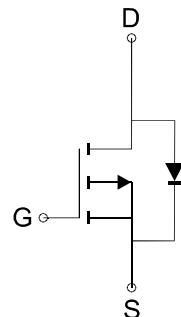
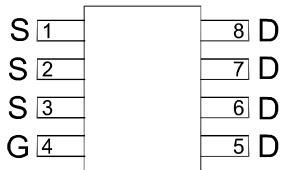
### FEATURES

1. -30V/-5.3A,  $R_{DS(ON)}=60\text{m}\Omega$  @  $V_{GS}=-10\text{V}$
2. -30V/-4.2A,  $R_{DS(ON)}=100\text{m}\Omega$  @  $V_{GS}=-4.5\text{V}$

### PIN CONFIGURATION

(SOP-8)

Top View



P-Channel MOSFET

### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ Unless Otherwise Noted)

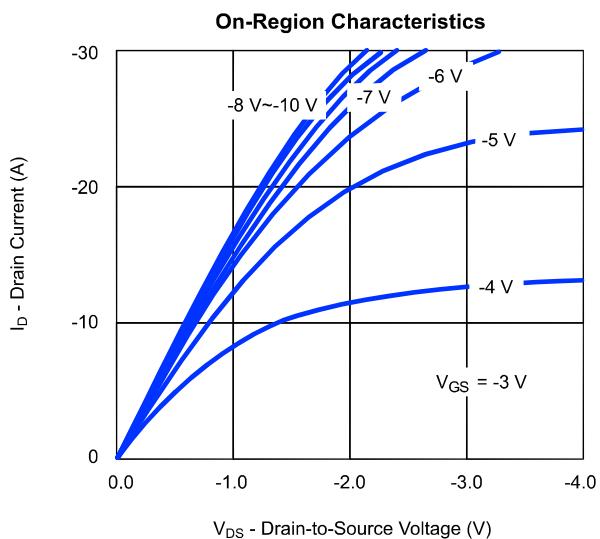
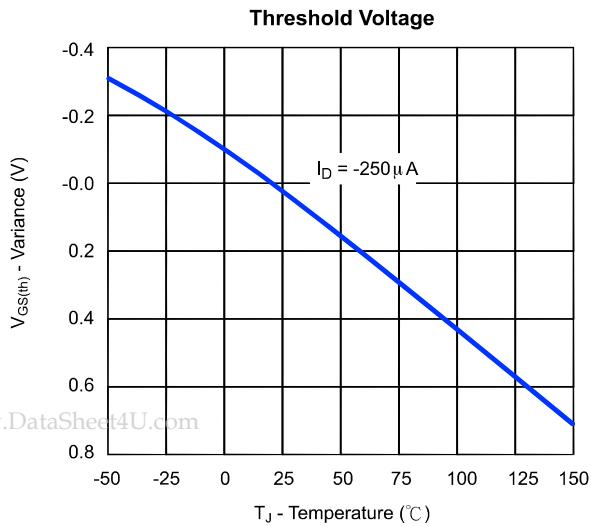
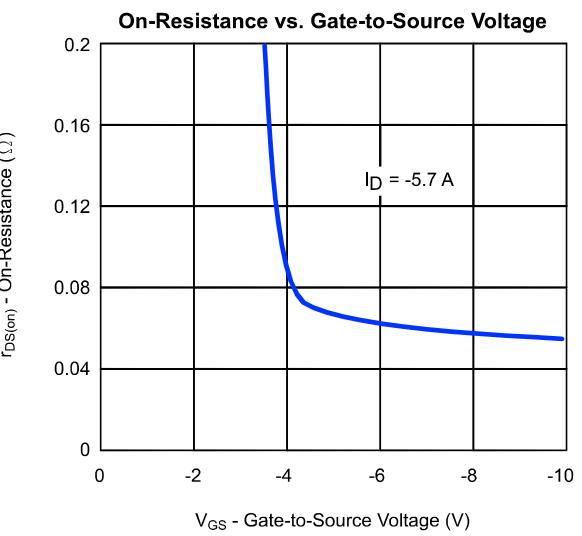
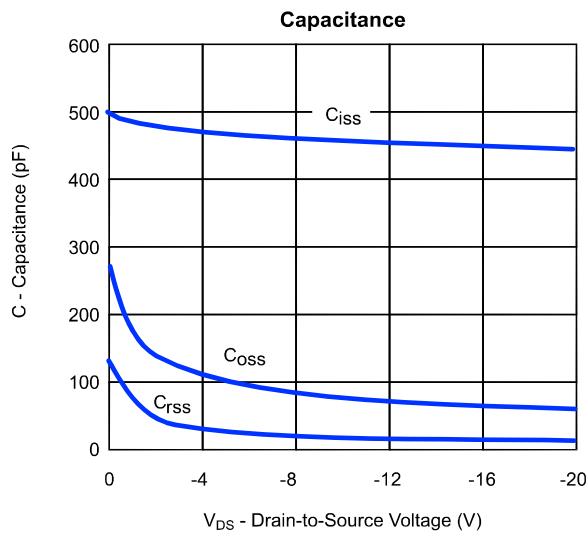
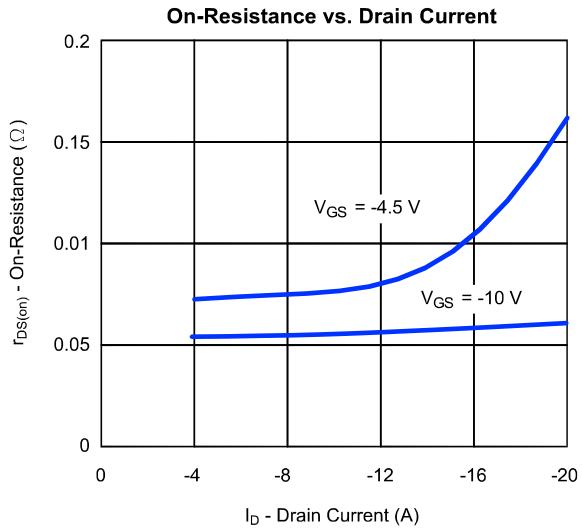
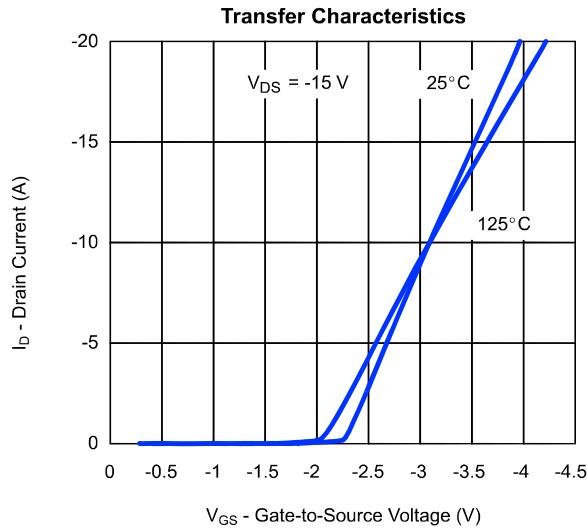
Parameter	Symbol	10 secs	Steady State	Unit
Drain-Source Voltage	$V_{DSS}$		-30	V
Gate-Source Voltage	$V_{GSS}$		$\pm 20$	V
Continuous Drain Current $T_A=25^\circ\text{C}$	$I_D$		-5.3	A
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$		-20	A
Maximum Power Dissipation $T_A=25^\circ\text{C}$	$P_D$		2.5	W
Operating Junction Temperature	$T_J$		-55 to 150	
Junction-to-Case Thermal Resistance	$R_{\theta JC}$		30	/W
Junction-to-Ambient Thermal Resistance (PCB mounted) <sup>2)</sup>	$R_{\theta JA}$		50	/W

Notes: 1. Maximum DC current limited by the package; 2. 1-in<sup>2</sup> 2oz PCB board

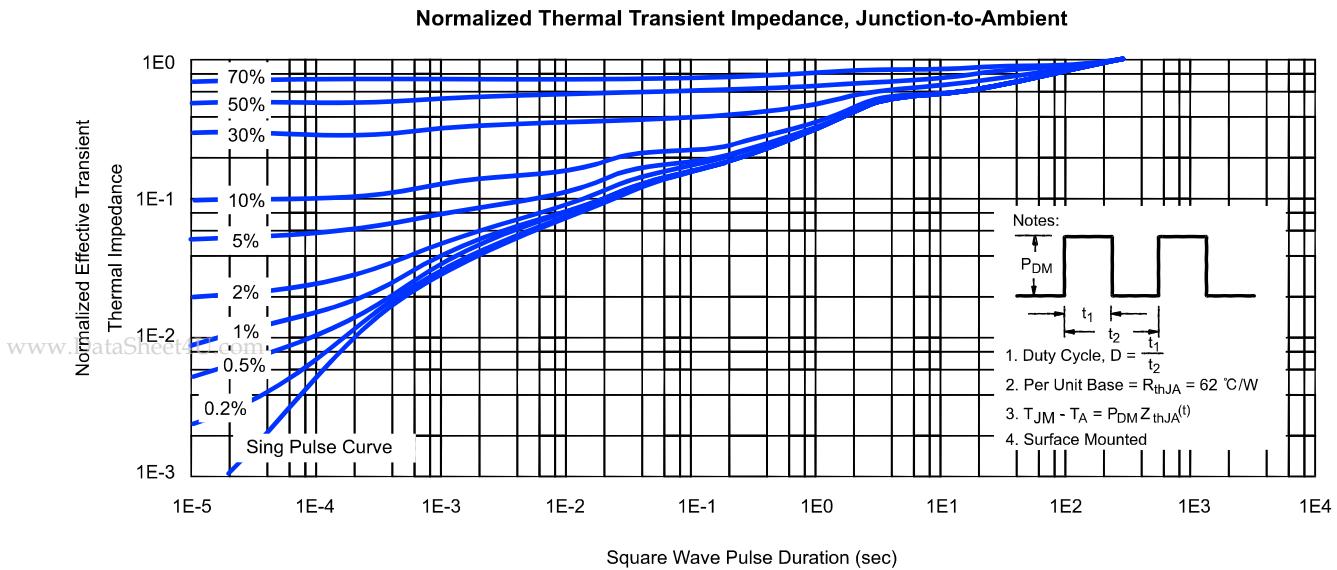
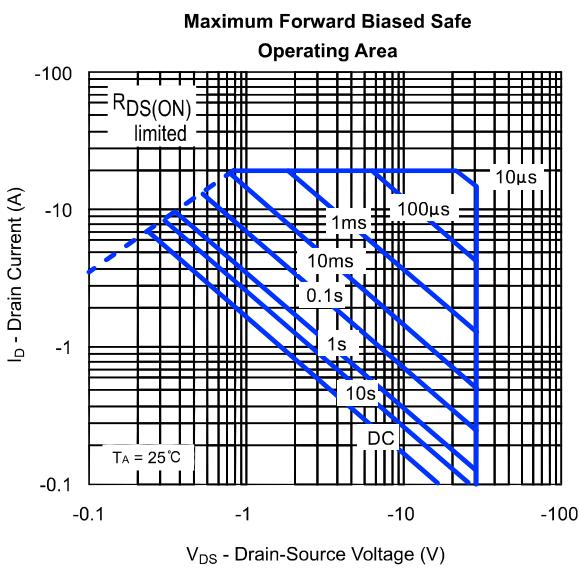
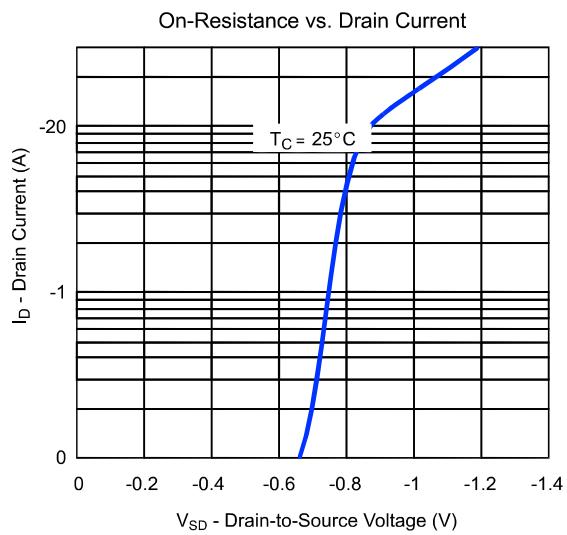
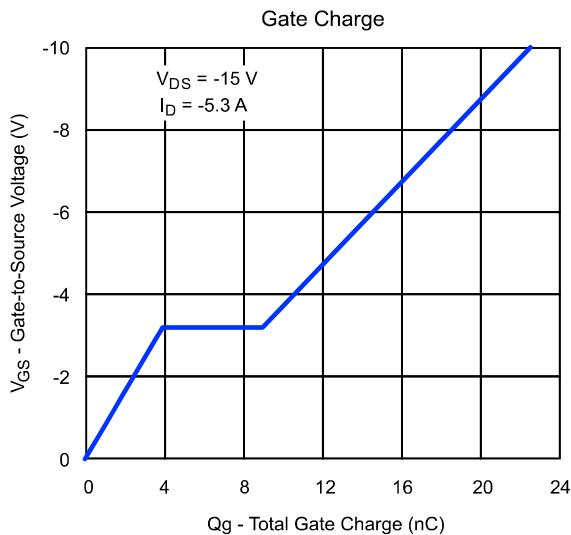
### Electrical Characteristics ( $T_A = 25^\circ C$ Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
<b>STATIC</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250 \mu A$	-30			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250 \mu A$	-1.0	-2.2	-3.0	V
$I_{GSS}$	Gate Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-24V, V_{GS}=0V$			-1	$\mu A$
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=-10V, I_D=-5.3A$		50	65	m
		$V_{GS}=-4.5V, I_D=-4.2A$		90	110	
$G_{FS}$	Forward Transconductance	$V_{DS}=-15V, I_D=-5.3A$	4	7		s
<b>DYNAMIC</b>						
$R_g$	Gate resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$		3.5		$\Omega$
$C_{iss}$	Input capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1.0MHz$		450	490	'pF
$C_{oss}$	Output Capacitance			70		
$C_{rss}$	Reverse Transfer Capacitance			20		
$Q_g$	Total Gate Charge	$V_{DS}=-15V, V_{GS}=-10V, I_D=-5.3A$		12	15	nC
$Q_{gs}$	Gate-Source Charge			2.7		
$Q_{gd}$	Gate-Drain Charge			3.7		
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=-15V, R_L=15\Omega, I_D=-1A, V_{GEN}=-10V, R_G=6\Omega$		35	44	ns
$t_r$	Turn-On Rise Time			18	22	
$t_{d(off)}$	Turn-Off Delay Time			37	46	
$t_f$	Turn-Off Fall Time			3.5	5	

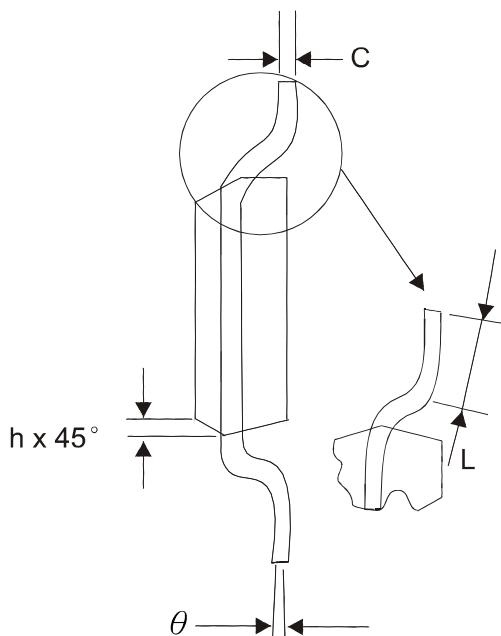
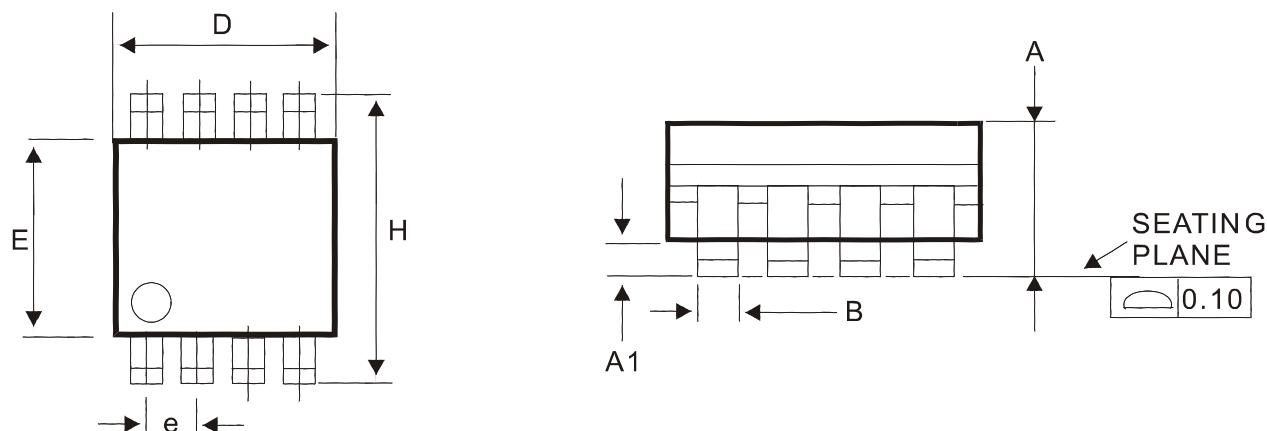
### Typical Characteristics (T<sub>J</sub> = 25° C Noted)



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## SOP-8 Package Outline



DIM	MILLIMETERS	
	MIN	MAX
A	1.35	1.75
A1	0.10	0.25
B	0.35	0.49
C	0.18	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.25
	0°	7°